



HJ122

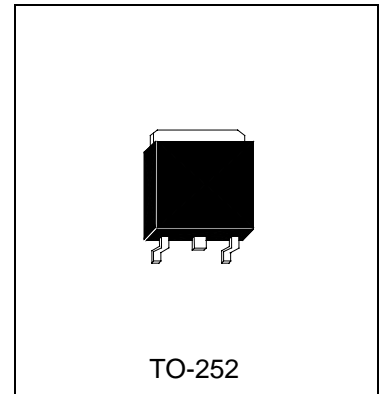
NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HJ122 is designed for use in general purposes and low speed switching applications.

Features

- High DC current gain
- Built-in a damper diode at E-C



Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature +150 °C
- Maximum Power Dissipation
 Total Power Dissipation (Tc=25°C) 20 W
- Maximum Voltages and Currents (Ta=25°C)
 BVCBO Collector to Base Voltage 100 V
 BVCEO Collector to Emitter Voltage 100 V
 BVEBO Emitter to Base Voltage 5 V
 IC Collector Current 5 A

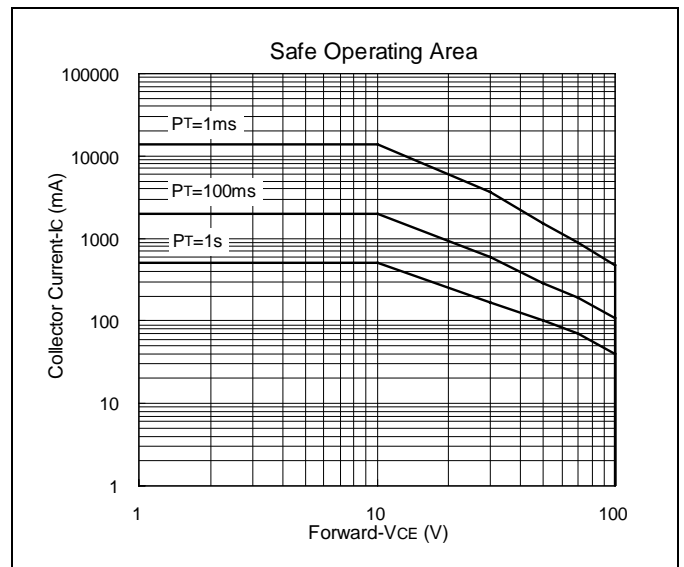
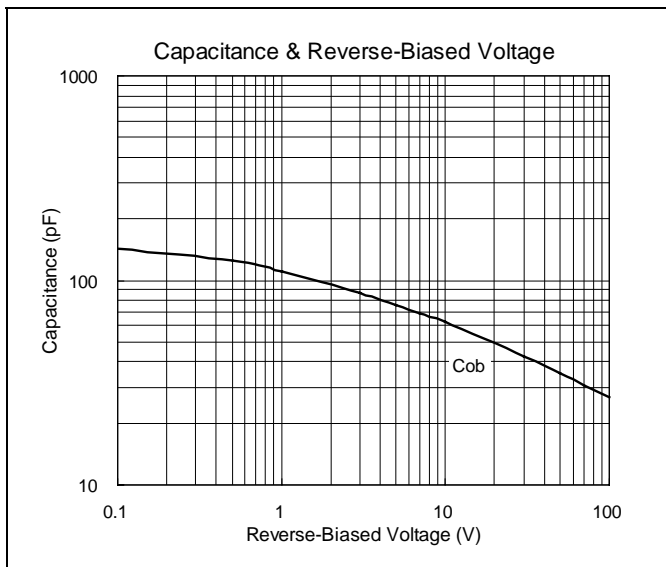
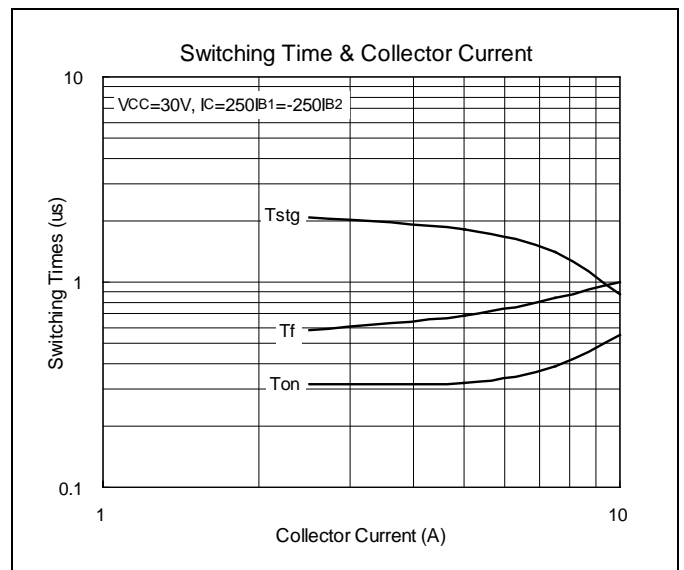
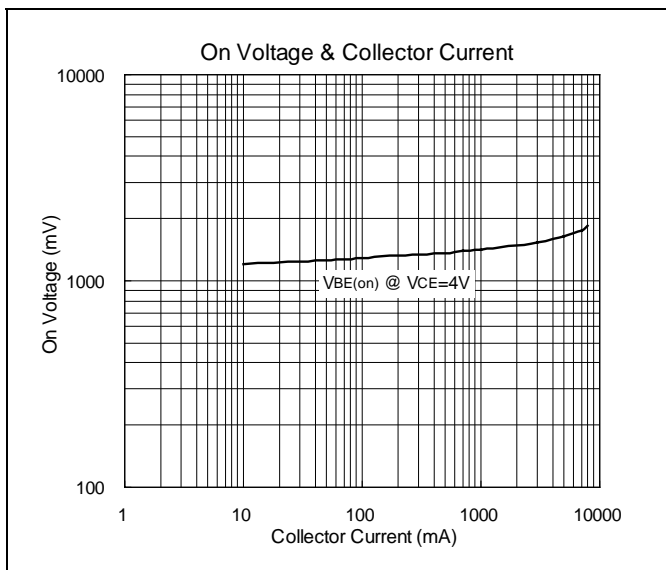
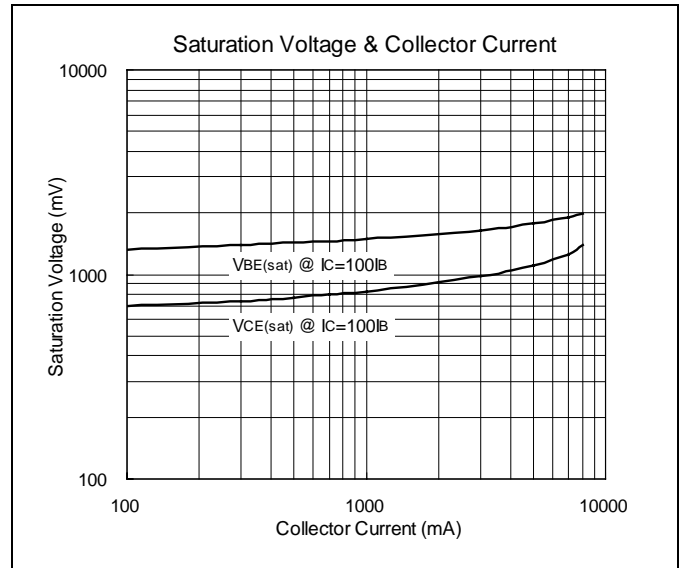
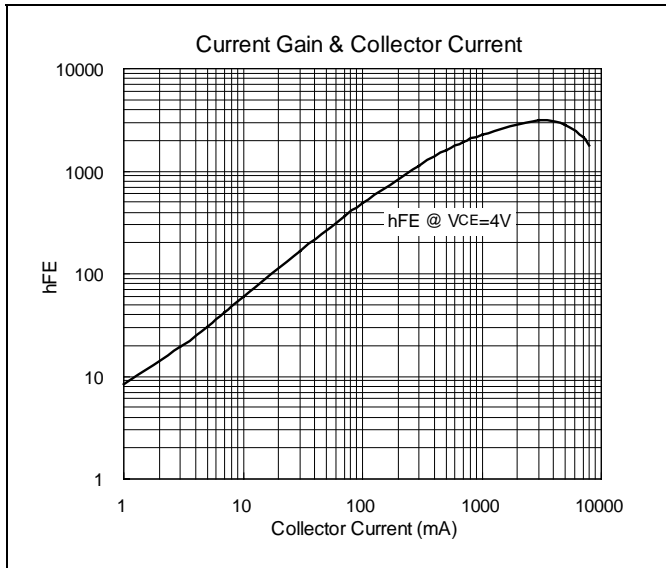
Characteristics (Ta=25°C)

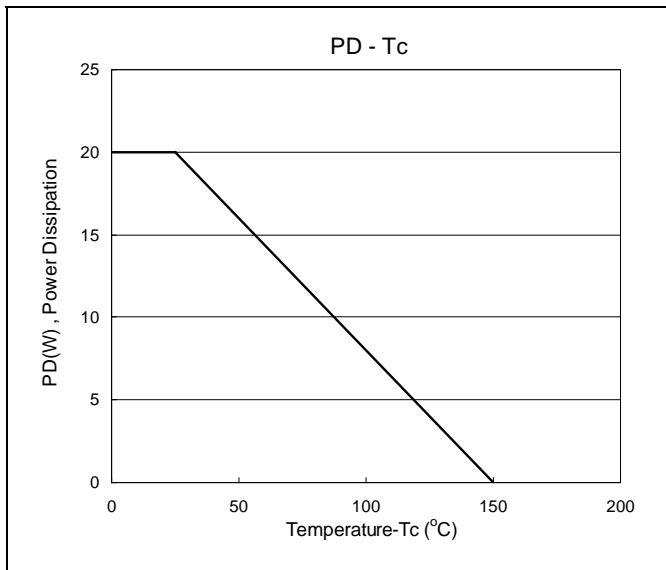
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	100	-	-	V	IC=1mA
BVCEO	100	-	-	V	IC=30mA
BVEBO	5	-	-	V	IE=1mA
ICBO	-	-	10	uA	VCB=100V
ICEO	-	-	10	uA	VCE=50V
IEBO	-	-	2	mA	VEB=5V
*VCE(sat)1	-	-	2	V	IC=4A, IB=16mA
*VCE(sat)2	-	-	4	V	IC=8A, IB=80mA
*VBE(sat)	-	-	4.5	V	IC=8A, IB=80mA
*VBE(on)	-	-	2.8	V	VCE=4V, IC=4A
*hFE1	1	-	12	K	VCE=4V, IC=4A
*hFE2	100	-	-		VCE=4V, IC=8A
Cob	-	-	200	pF	VCB=10V

*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%



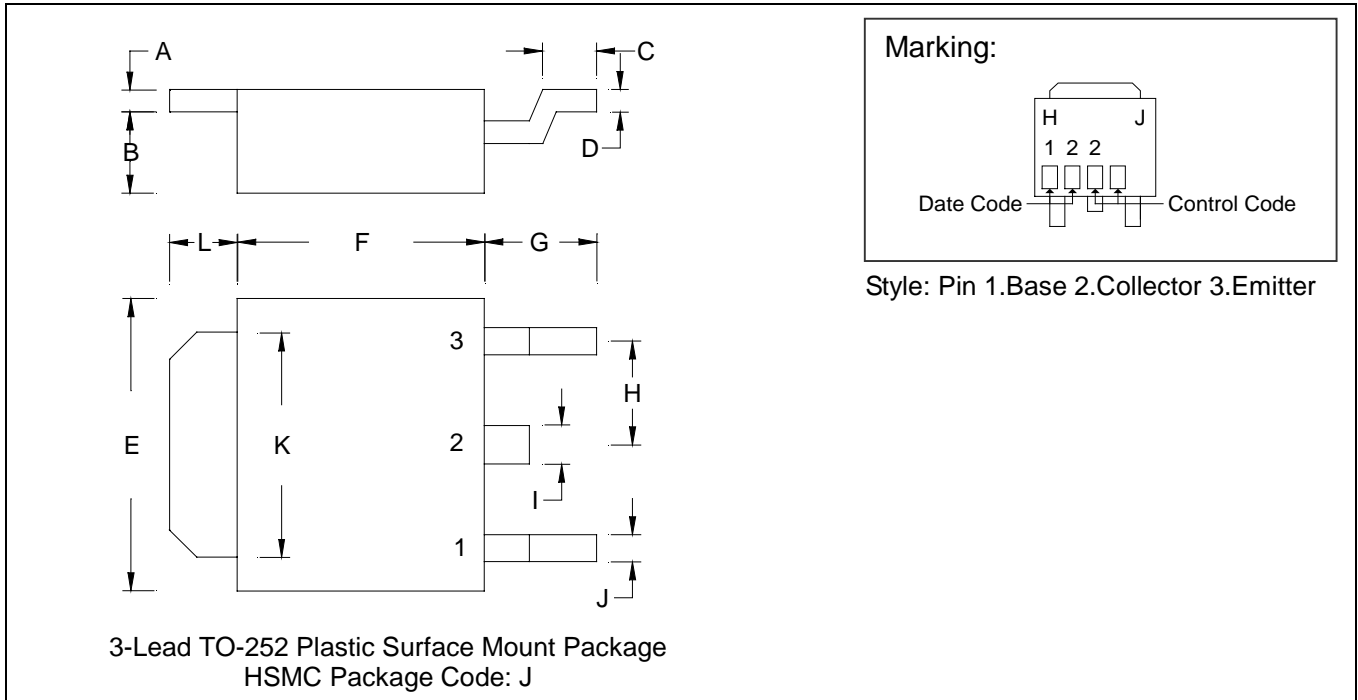
Characteristics Curve







TO-252 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.0866	0.1102	2.20	2.80
B	0.0650	0.0768	1.65	1.95	H	-	*0.0906	-	*2.30
C	0.0354	0.0591	0.90	1.50	I	-	0.0354	-	0.90
D	0.0177	0.0236	0.45	0.60	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2125	0.2283	5.40	5.80	L	0.0551	0.0630	1.40	1.60

- Notes: 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
 2.Controlling dimension: millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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Head Office And Factory:

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
Tel: 886-3-5983621~5 Fax: 886-3-5982931

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